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#### SLUS177B-MARCH 1999-REVISED SEPTEMBER 2008

## **DUAL CHANNEL POWER DRIVER**

### **FEATURES**

- Two Independent Drivers
- 1.5 A Totem Pole Outputs
- Inverting and Non-Inverting Inputs
- 40 ns Rise and Fall Into 1000 pF
- High-Speed, Power MOSFET Compatible
- Low Cross-Conduction Current Spike

- Analog Shutdown With Optional Latch
- Low Quiescent Current
- 5 V to 40 V Operation
- Thermal Shutdown Protection
- 16-Pin Dual-In-Line Package
- 20-Pin PLCC and CLCC Package

## DESCRIPTION

The UC1707 family of power drivers is made with a high-speed Schottky process to interface between low-level control functions and high-power switching devices–particularly power MOSFETs. These devices contain two independent channels, each of which can be activated by either a high or low input logic level signal. Each output can source or sink up to 1.5 A as long as power dissipation limits are not exceeded.

Although each output can be activated independently with its own inputs, it can be forced low in common through the action either of a digital high signal at the Shutdown terminal or a differential low-level analog signal. The Shutdown command from either source can either be latching or not, depending on the status of the Latch Disable pin.

Supply voltage for both  $V_{IN}$  and  $V_C$  can independently range from 5 V to 40 V.

These devices are available in two-watt plastic "bat-wing" DIP for operation over a 0°C to 70°C temperature range and, with reduced power, in a hermetically sealed cerdip for –55°C to +125°C operation. Also available in surface mount DW, Q, L packages.

	()	
INV.	N.I.	OUT
Н	Н	L
L	Н	Н
Н	L	L
L	L	L

#### TRUTH TABLE (Each Channel)<sup>(1)</sup>

(1)  $\underline{OUT} = \overline{INV}$  and N.I.  $\overline{OUT} = INV$  or N.I.



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### **BLOCK DIAGRAM**



### **CONNECTION DIAGRAMS**







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#### **ABSOLUTE MAXIMUM RATINGS**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>IN</sub>	Supply voltage	N/J package		40	V	
V <sub>C</sub>	Collector supply voltage	N/J package		40	V	
	Output current (each output, source or sink) steady-state	N/J package		±500	mA	
	Peak transient	N package		±1.5	А	
	Peak transient	J package		±1.0	А	
	Constitute discharge energy	N package		20		
	Capacitive discharge energy	J package		m.		
	Digital inputs <sup>(1)</sup>	N/J-package		5.5	V	
	Analog stop inputs	N/J package		V <sub>IN</sub>		
	Dower discinction at T 25°C	N package		2	W	
	Power dissipation at $T_A = 25^{\circ}C$	J package		1	vv	
	Demonstration at T (lands (see a) $25\%$ (1)	N package		5	W	
	Power dissipation at T (leads/case) = $25^{\circ}C^{(1)}$	J package		2	vv	
	Operating temperature range		-55	+125	°C	
	Storage temperature range		-65	+150	°C	
	Lead temperature (soldering, 10 seconds)			300	°C	

(1) All voltages are with respect to the four ground pins which must be connected together. All currents are positive into, negative out of the specified terminal. Digital drive can exceed 5.5 V if input current is limited to 10 mA. Consult packaging section of databook for thermal limitations and considerations of package.

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise stated, these specifications apply for  $T_A = -55^{\circ}C$  to  $+125^{\circ}C$  for the UC1707,  $-25^{\circ}C$  to  $+85^{\circ}C$  for the UC2707, and 0°C to  $+70^{\circ}C$  for the UC3707;  $V_{IN} = V_C = 20$  V.  $T_A = T_J$ .

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>IN</sub>	Supply current	V <sub>IN</sub> = 40 V		12	15	mA
V <sub>C</sub>	Supply current	$V_{C} = 40 V$ , outputs low		5.2	7.5	mA
V <sub>C</sub>	Leakage current	$V_{IN} = 0$ , $V_C - 30$ V, no load		0.05	0.1	mA
	Digital input low level				0.8	V
	Digital input high level		2.2			V
	Input current	V <sub>1</sub> = 0		-0.06	-1.0	mA
	Input leakage	V <sub>1</sub> = 5 V		0.05	0.1	mA
V V		I <sub>O</sub> = -50 mA			2.0	
v <sub>C</sub> – v <sub>O</sub>	Output high sat.	I <sub>O</sub> = -500 mA			2.5	V
N/	Output law act	I <sub>O</sub> = -50 mA			0.4	V
Vo	Output low sat.	I <sub>O</sub> = -500 mA			2.5	V
	Analog threshold	V <sub>CM</sub> = 0 to 15 V	100	130	160	mV
	Input bias current	V <sub>CM</sub> = 0		-10	-20	μA
	Thermal shutdown			155		°C
	Shutdown threshold	Pin 7 input	0.4	1.0	2.2	V
	Latch disable threshold	Pin 3 input	0.8	1.2	2.2	V



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### **TYPICAL SWITCHING CHARACTERISTICS**

 $V_{\text{IN}}$  =  $V_{\text{C}}$  = 20 V,  $T_{\text{A}}$  = 25°C. Delays measured to 10% output change.

PARAMETER	TEST CONDITIONS	OUT	OUTPUT CL =			
From Inv. Input to Output		open	1.0	2.2	nF	
Rise time delay		40	50	60	ns	
10% to 90% rise		25	40	50	ns	
Fall time delay		30	40	50	ns	
90% to 10% fall		25	40	50	ns	
From N.I. Input to Output						
Rise time delay		30	40	50	ns	
10% to 90% rise		25	40	50	ns	
Fall time delay		45	55	65	ns	
90% to 10% fall		25	40	50	ns	
V <sub>C</sub> cross-conduction current spike duration	Output rise	25			ns	
	Output fall	0			ns	
Analog shutdown delay	Stop non-Inv. = 0 V	180			ns	
	Stop Inv. = 0 to 0.5 V	180			ns	
Digital shutdown delay	2 V input on Pin 7	50			ns	

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### SIMPLIFIED INTERNAL CIRCUITRY







Figure 2. Typical Digital Input Gate





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### SIMPLIFIED INTERNAL CIRCUITRY (continued)



Figure 4. Use of the Shutdown Pin

#### SHUTDOWN CIRCUIT DESCRIPTION

The function of the circuitry is to be able to provide a shutdown of the device. This is defined as functionality that will drive both outputs to the low state. There are three different inputs that govern this shutdown capability.

- Analog Stop Pins The differential inputs to this comparator provide a way to execute a shutdown.
- Latch Disable Pin Assuming that the Shutdown pin is left open, a high on this pin disables the latching functionality of the Analog Stop shutdown. A low on this pin enables the latching functionality of the Analog Stop shutdown occurs through the Analog Stop circuit while Latch Disable is high, then the outputs will go low, but will return to normal operation as soon as the Analog Stop circuit allows it. If a shutdown occurs through the Analog Stop circuit while Latch Disable is low, then the outputs will go low and remain low even if the Analog Stop circuit no longer drives the shutdown. The outputs will remain "latched" low (in shutdown) until the Latch Disable goes high and the Analog Stop circuit allows it to return from shutdown or the VIN voltage is cycled to 0V and then returned above 5V.
- Shutdown Pin This pin serves two purposes.
  - 1. It can be used as an output of the Analog Stop circuit.
  - 2. It can be used as an input to force a shutdown or to force the device out of shutdown. This pin can override both the Analog Stop circuit as well as the Latch Disable Pin. When driving hard logic levels into the Shutdown pin, the Latch Disable functionality will be overridden and the Latch Disable will not function as it does when used in conjunction with the Analog Stop circuit. When the Shutdown pin is high, the outputs will be in the low state (shutdown). When the Shutdown pin is low (hard logic low) the outputs will operate normally, regardless of the state of the Latch Disable pin or the Analog Stop pins.

In order to use the Shutdown Pin with the Latch Disable functional it is necessary to use either a diode in series with the Shutdown signal or to use an open collector pull-up so that the Shutdown pin is not pulled low. This configuration will allow the Latch Disable function to work with the Shutdown pin.



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## SIMPLIFIED INTERNAL CIRCUITRY (continued) UG1707 SHUTDOWN TRUTH TABLE

ANALOG STOP LOGIC	SHULDOWN LATCHDISABLE		PREVIOUS STATE OF OUTPUT	OUTPUT		
Х	0	Х	Х	Follows Input Logic		
Х	1	Х	Х	Low (Shutdown)		
1	Open	Х	Х	Low (Shutdown)		
0	Open	0	Shutdown	<sup>(1)</sup> Latched Shutdown		
0	Open	0	Normal	Follows Input Logic		
0	Open	1	Х	Follows Input Logic		

(1) If the output was previously in Shutdown and Latch Disable was low and stays low, then even if the Analog Stop Logic is changed or the Shutdown pin is open, the outputs will remain in Shutdown.



Figure 5. Transformer Coupled Push-Pull MOSFET Drive Circuit



### Figure 6. Current Limiting



Figure 7. Over-Voltage Protection



Figure 8. Power MOSFET Drive Circuit



Figure 9. Charge Pump Circuits





Figure 10. Power Bipolar Drive Circuit



Figure 11. Transformer Coupled MOSFET Drive Circuit

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Figure 12. Power MOSFET Drive Circuit Using Negative Bias Voltage and Level Shifting to Ground Reference PWM

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## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87619012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87619012A UC1707L/ 81032	Samples
5962-8761901EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761901EA UC1707J/80900	Samples
5962-8761901V2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 8761901V2A UC1707L QMLV	Samples
5962-8761901VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761901VE A UC1707JQMLV	Samples
5962-8761903V2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 8761903V2A UC1707L-SP	Samples
5962-8761903VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761903VE A UC1707J-SP	Samples
5962-8761903VFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761903VF A UC1707W-SP	Samples
UC1707J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1707J	Samples
UC1707J883B	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1707J/883B	Samples
UC1707L	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1707L	Samples
UC1707L883B	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1707L/ 883B	Samples
UC2707DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW	Samples
UC2707DWTR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2707DW	Samples
UC2707N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	UC2707N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC2707NG4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	UC2707N	Samples
UC3707DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW	Samples
UC3707DWTR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3707DW	Samples
UC3707J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	0 to 70	UC3707J	Samples
UC3707N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	UC3707N	Samples
UC3707NG4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	UC3707N	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



## PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF UC1707, UC1707-SP, UC3707, UC3707M :

- Catalog : UC3707, UC1707, UC3707M, UC3707
- Military : UC1707, UC1707
- Space : UC1707-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



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STRUMENTS

### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2707DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
UC3707DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1



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# PACKAGE MATERIALS INFORMATION

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2707DWTR	SOIC	DW	16	2000	356.0	356.0	35.0
UC3707DWTR	SOIC	DW	16	2000	356.0	356.0	35.0

## **TEXAS INSTRUMENTS**

\*All dimensions are nominal

UC2707NG4

UC3707DW

UC3707N

UC3707NG4

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W (mm)

12.06

12.06

12.06

15.24

26.16

12.06

12.06

12.83

13.97

13.97

12.83

13.97

13.97

T (µm)

2030

2030

2030

13440

6220

2030

2030

5080

11230

11230

5080

11230

11230

B (mm)

NA

NA

NA

NA

NA

NA

NA

6.6

4.32

4.32

6.6

4.32

4.32

506

507

506

506

3-Jun-2022

## TUBE



## **B** - Alignment groove width

Device	Package Name	Package Type	Pins	SPQ	L (mm)
5962-87619012A	FK	LCCC	20	1	506.98
5962-8761901V2A	FK	LCCC	20	1	506.98
5962-8761903V2A	FK	LCCC	20	1	506.98
5962-8761903VEA	J	CDIP	16	1	506.98
5962-8761903VFA	W	CFP	16	1	506.98
UC1707L	FK	LCCC	20	1	506.98
UC1707L883B	FK	LCCC	20	1	506.98
UC2707DW	DW	SOIC	16	40	507
UC2707N	N	PDIP	16	25	506

PDIP

SOIC

PDIP

PDIP

16

16

16

16

25

40

25

25

Ν

DW

Ν

Ν

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